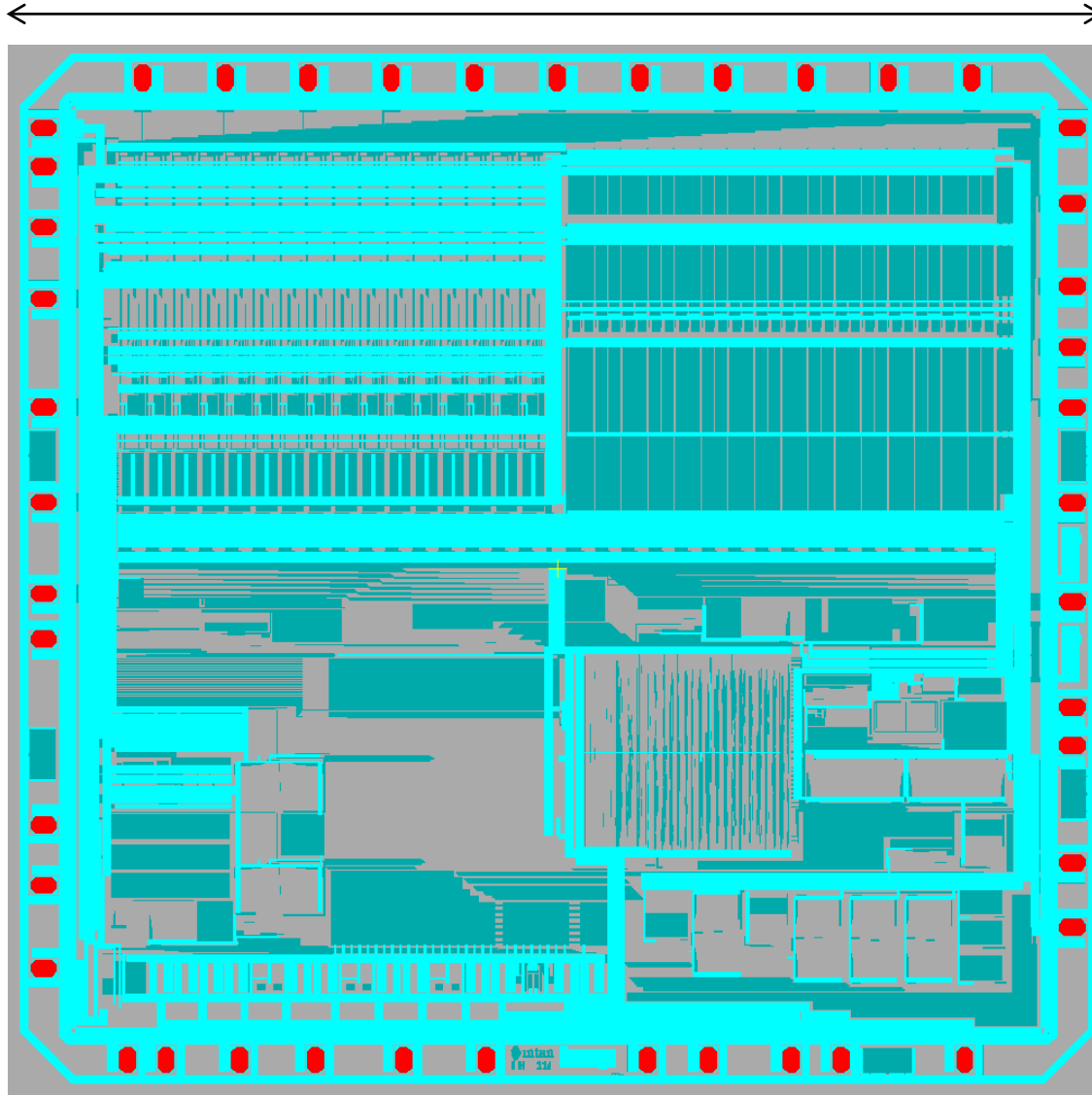


Intan Technologies RHS2116 Bare Die

Approximately 4.9 mm



Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

Blue, Green = top metal layers (highly visible)

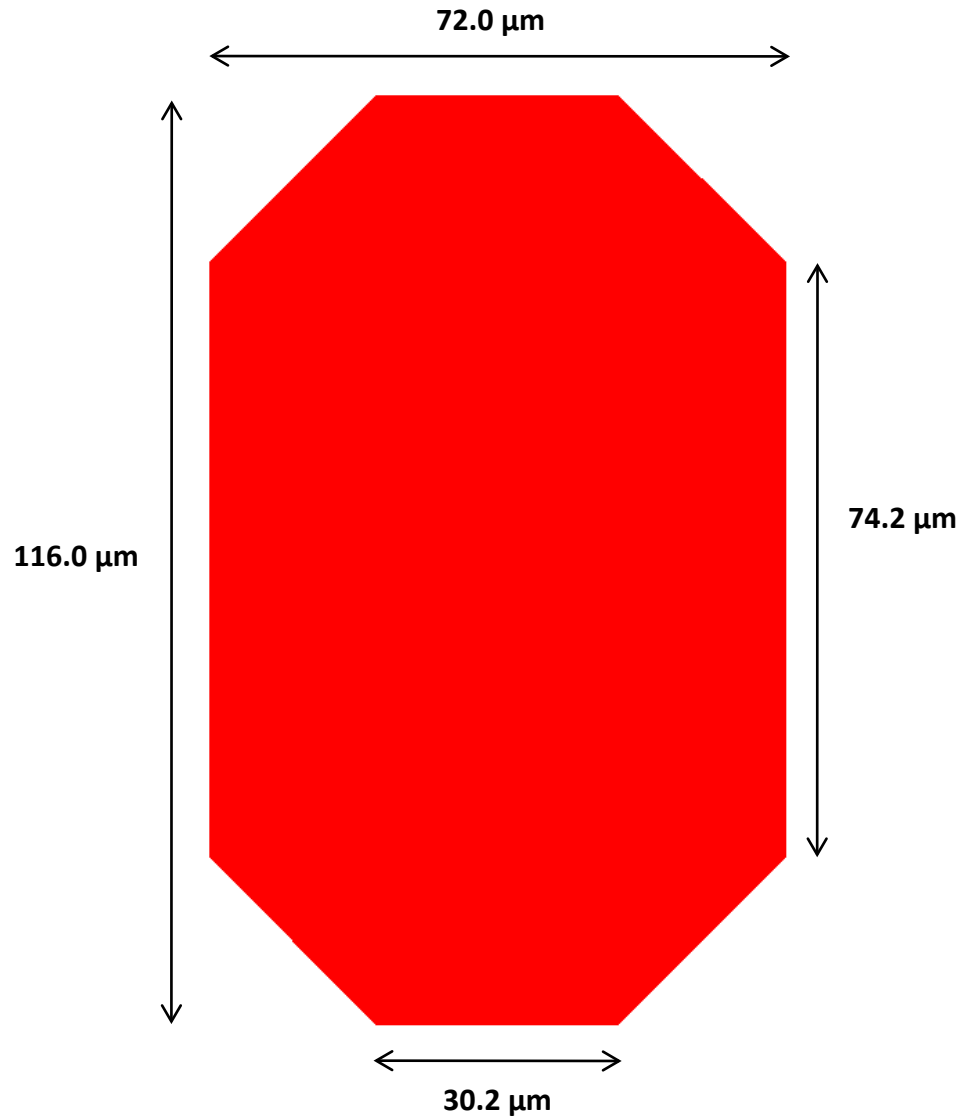
Red = glass openings for bond pads

Approximately 4.7 mm

Each die is 0.20 mm (8 mils) thick

Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper) Thickness: 2.9 μm



Minimum bond pad pitch (center to center): 173 μm